

REMARKS

Claims 61 and 64 have been amended, and claims 65-80 have been newly added. Claims 61-80 are now pending in the application. Applicant respectfully requests reexamination and reconsideration of the application in light of the amendments and the following remarks.

It should be appreciated that—with the exception of the requirement that the special contact pads be smaller than the bond pads—all of the amendments made to claims 61 and 64 were not made for patentability reasons. Rather, all of the amendments were made to broaden the scope of the claims or to clarify the claims.

Turning first to the objection to the Information Disclosure Statement (IDS) filed December 29, 2000, Applicants submit a new Information Disclosure Statement herewith, which includes all of the references cited in the December 29, 2000 IDS. As explained in the newly filed IDS, however, copies of the listed references are NOT provided because all of the listed references were cited in the parent application, US serial no. 09/224,169. As stated in the MPEP, Applicants are not required to provide copies of references that were also cited in a parent application. See 37 CFR § 1.98(d). Therefore, Applicants request that the Examiner initial and return the new IDS form submitted herewith.

Turning next to the objection to the drawings, Applicants point out that the specification reads "PCB 2810" at lines 15 and 18 on page 31. Thus, the reference number 2810 is mentioned in the description. Therefore, Applicants ask that the objection to the drawings be withdrawn.

Applicants believe that the amendments to claim 61 moot the objection to that claim.

Claims 61-64 have been rejected as unpatentable in view of U.S. Patent No. 5,874,662 ("Eldridge"). To the extent this rejection might be applied to the claims as amended, Applicants respectfully traverse these rejections.

Independent claim 61 and newly added independent claim 72 recite a socket having two different sets of resilient contact structures or means. One set contacts "bond pads" on a "first electronic component," and the other set contacts "special contact pads" also on the "first electronic component." Both claim 61 and claim 72 require that the special contact pads be "smaller" than the "bond pads." Eldridge does not teach that its bond

pads 526 (what the Examiner has referred to as being both "a first plurality of contact points" and "a second plurality of contact points") include one group of pads that are smaller than another group of pads. Nor does Eldridge suggest or motive making one group of bond pads 526 smaller than another group of bond pads 526. Therefore, independent claims 61 and 72 and the claims that depend therefrom patentably distinguish over Eldridge.

It should be noted that providing two differently sized pads on an electronic component provides advantages. For example, the smaller pads may allow for the use of smaller electrostatic discharge protection circuits than the larger pads. Indeed, electrostatic discharge protection may be dispensed with for the smaller pads. Similarly, the smaller pads may allow for the use of smaller input/output buffer circuitry or smaller driver circuitry. As another example, the location of smaller pads on the electronic component is usually less restricted than larger pads.

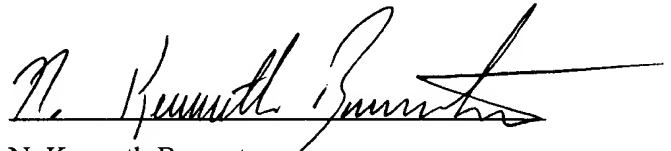
In view of the foregoing, Applicants respectfully submit that all claims pending in the application patentably distinguish over the cited and applied references and are in condition for allowance. If the Examiner believes that a discussion with Applicants' attorney would be helpful, the Examiner is invited to contact the undersigned at (925) 456-3915.

Although Applicant believes that all necessary extensions of time have been requested and fees have been authorized in papers filed herewith, Applicants hereby petition the Commissioner for any extension of time deemed necessary for acceptance of this paper, and Applicants authorize the Commissioner to charge any fee due in connection with the filing of this paper to Deposit Account No. 50-0285 (order no. P60D4-US).

Respectfully submitted,

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By:



N. Kenneth Burraston
Registration No. 39,923

FormFactor, Inc.
Legal Department
2140 Research Dr.
Livermore, CA 94550
925-294-4300
925-294-8147 Fax

Version With Markings To Show Changes Made

61. (Amended) A socket for releasably connecting a first electronic component to a second electronic component, comprising:

a first plurality of resilient contact structures extending [upward] from a [top] surface of a support substrate, the first plurality of resilient contact structures [for communicating signals with a first] configured to make electrical connections with a plurality of [contact points of] bond pads on the first electronic component;

a second plurality of resilient contact structures extending [upward] from the [top] surface of the support substrate, the second plurality of resilient contact structures [for communicating signals with a second] configured to make electrical connections with a plurality of [contact points of] special contact pads on the [second] first electronic component, wherein said special contact pads are smaller than said bond pads; and

a plurality of contact structures disposed on [a bottom] another surface of the support substrate for making electrical contact with said second electronic component, [selected] ones of the contact structures are connected [through the support substrate] to [selected] ones of the first plurality of resilient contact structures, and ones of the contact structures are connected to ones of the second plurality of resilient contact structures.

64. (Amended) The socket of claim 61, further comprising means for urging the first electronic component down onto the first and second resilient contact [elements] structures.